ABSOCIATION CONNECTING ELECTRONICS INDUSTRIES® INCLUSTRIES® INCLUSTRIES®	, Bannockb	urn, Illinois. A	All rights reserved un ntions.	nder both This level	documer parts, th	nt is a declaration	tion of the s encompasse	ubstances s all lowe	within the manufacture or level materials for w	rer listed i hich the r	item. Note: i nanufacture	f the item is an as r has engineering	ssembly with lower responsibility.	
				Form Type * Distribute					ials and Mfg Information					
Supplier Information														
Company name*	Company unique ID			U	Unique ID Authority					Response Date*				
onsemi										2024-05-18				
Contact Name Title - Con			itle - Contact			Phone - Contact*				Email -	Email - Contact*			
Product-Env-Stewards Product			Product Enviro Compliance			NA				Product-Env-Stewards@onsemi.com				
Authorized Representative* Title - Repr			e - Representative			Phone - Representative*			Email - Representative*					
Product-Env-Stewards Pro			Product Enviro Compliance			NA				Product-Env-Stewards@onsemi.com				
Requester Item Number	Mfr Item Number		Mfr Item Name		]	Effective Date	e Version	]	Manufacturing Site		Weight*	UOM	Unit Type	
	NCP4305	NCP4305QDR2G Secondary Side S Driver for High E		ynchronous Rectifica	tion 2 ologies	2024-05-18	18 PH1		PH1		71.91	mg	Each	
Manufacturing Proccess Information	n													
Terminal Plating / Grid Array Mate	minal Plating / Grid Array Material Terminal Base Alloy		Alloy J	-STD-020 MSL Rati	D-020 MSL Rating Pe		Peak Process Body Temperature Max Time at Peak		Tempera	ture Numb	per of Reflow Cy	cles		
Matte Tin (Sn) - annealed CU Alle		CU Alloy	Alloy 3			<b>260</b> C		С	30 seco		nds 3			
Comments														
ATTENTION: MSL 3 Rated item requires H	Bake and D	ry Pack (afte	r electrical test)											
For more information regarding material co	mposition	please refer to	page 3											

RoHS Material Composition Declaration				Declaration Type *	Detailed					
Directive 2015/863/EU amending RoHS Directive 2011/65/EU	RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Dibutyl phthalate (DBP), Dibutyl phthalate (DBP), Dibutyl phthalate (DBP).									
cadmium, hexavalentchromium, polybrominate contains a RoHS restricted substance inexcess encompass all such components. Supplier certif as of the date that Supplier completes this form Company acknowledges that Supplier may hav independently verified information provided by certification in this paragraph. If the Company a	ed biphenyls and/or polybrominated dip of an applicable quantity limit, please ir ies that it gathered the information it pro- .Supplier acknowledges that Company e relied on informationprovided by othe v others, Supplier agrees that, at a minin and the Supplier enter into a written agre pource of the Supplier's liability and the	henyl ethers (each a " ndicate below which, i ovides in this form us will rely on this certifiers in completing this num, itssuppliers have eement with respect to Company's remedies	RoHS restricted substance") in exce if any, RoHS exemption you believe ing appropriate methods to ensure if ication in determining the complian form, and that Supplier may not have e provided certifications regarding the to the identified part, the terms and co for issues that arise regarding inform	ce of its products with European Union membe	ove. If a homogeneous material within the part er level components, the declaration shall l correct to the best of its knowledge and belief, r state laws that implement the RoHS Directive. wever, in situations where Supplier has not tions are at least as comprehensive as the anty rights and/or remedies provided as part of					
RoHS Declaration * 1 - Item(s)	does not contain RoHS restricted substa	on above	Supplier Acceptance	* Accepted						
Exemption: If the declared item does not con applicable exemptions.	ntain RoHS restricted substances per	the definition above	except for defined RoHS exempti	ons, then select the corresponding response i	n the RoHS Declaration above and choose all					
Exemption List Version	EL-2011/534/EU									
Declaration Signature										
Instructions: Complete all of the required fin Requester) and click on Submit Form to have	elds on all pages of this form. Select the form returned to the Requester	he "Accepted" on th	e Supplier Acceptance drop-down	. This will display the signature area. Digital	lly sign the declaration (if required by the					
Supplier Digital Signature Ra	stislav Drska	Le								

## Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	1.33	mg	Supplier	Silicon (Si)	7440-21-3		1.33	mg
Die Attach	2.4	mg	Supplier	Organic peroxide	3006-86-8		0.018	mg
			Supplier	Diluent B	Proprietary Data		0.12	mg
			Supplier	Diluent A	Proprietary Data		0.096	mg
			Supplier	Dicyandiamine	461-58-5		0.006	mg
			Supplier	Aluminum Trioxide (Al2O3)	1344-28-1		1.92	mg
			Supplier	Formaldehyde Polymer	9003-36-5		0.24	mg
Lead Frame	37.61	mg	Supplier	Silver (Ag)	7440-22-4		0.1128	mg
			Supplier	Zinc (Zn)	7440-66-6		0.0715	mg
			Supplier	Iron (Fe)	7439-89-6		0.9741	mg
			Supplier	Copper (Cu)	7440-50-8		36.399	mg
			Supplier	Phosphorus (P)	7723-14-0		0.0527	mg
Mold Compound-Black	28.58	mg		Epoxy resin	proprietary data		1.429	mg
			Supplier	Phenolic Resin	Proprietary Data		1.429	mg
			Supplier	Ortho Cresol Novolac Resin	29690-82-2		0.5716	mg
			Supplier	Carbon Black (C)	1333-86-4		0.1429	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		25.0075	mg
lating	1.89	mg	Supplier	Tin (Sn)	7440-31-5		1.89	mg
Wire Bond	0.1	mg	Supplier	Palladium (Pd)	7440-05-3		0.0021	mg
			Supplier	Gold (Au)	7440-57-5		0.0003	mg
			Supplier	Copper (Cu)	7440-50-8		0.0976	mg